

WHAT IS CLAIMED IS:

1. A chip on photosensitive device package structure, comprising:
 - a photosensitive device having an illumination area and a non-illumination area;
 - a transparent plate having a first surface and a corresponding second surface,

5 wherein the transparent plate is set on the photosensitive device with the first surface covering the illumination area and the non-illumination area; and

 - a chip set on the second surface of the transparent plate above the non-illumination area.
2. The package structure of claim 1, wherein the package further comprises a
10 memory device set on the second surface of the transparent plate above the non-illumination area.
3. The package structure of claim 1, wherein the photosensitive device has an array of photodiodes positioned within the illumination area.
4. The package structure of claim 1, wherein the non-illumination area is located
15 at the periphery of the illumination area.
5. The package structure of claim 1, wherein the photosensitive device comprises a charge coupled device (CCD).
6. The package structure of claim 1, wherein the photosensitive device comprises a complementary metal-oxide-semiconductor (CMOS) image sensor.

20 7. The package structure of claim 1, wherein material constituting the transparent plate comprises one of glass and acrylic material.

8. The package structure of claim 1, wherein the chip comprises a signal-processing chip.

9. An electrical package structure, comprising:

a circuit substrate;
a photosensitive device set on the circuit substrate and electrically connected to the circuit substrate through a plurality of first conductive wires, wherein the photosensitive device has an illumination area and a non-illumination area;

5 a transparent plate having a first surface and a corresponding second surface, wherein the transparent plate is set on the photosensitive device with the first surface covering the illumination area and the non-illumination area; and

 a chip set on the second surface of the transparent plate above the non-illumination area and electrically connected to the circuit substrate through a plurality of
10 second conductive wires.

10. The electrical package structure of claim 9, wherein the package further comprises a memory device set on the second surface of the transparent plate above the non-illumination area.

11. The electrical package structure of claim 9, wherein the photosensitive
15 device has an array of photodiodes set within the illumination area.

12. The electrical package structure of claim 9, wherein the non-illumination area is located at the periphery of the illumination area.

13. The electrical package structure of claim 9, wherein the photosensitive device comprises a charge coupled device (CCD).

20 14. The electrical package structure of claim 9, wherein the photosensitive device comprises a complementary metal-oxide-semiconductor (CMOS) image sensor.

15. The electrical package structure of claim 9, wherein material constituting the transparent plate comprises one of glass and acrylic material.

16. The electrical package structure of claim 9, wherein the chip comprises a signal-processing chip.

17. The electrical package structure of claim 9, wherein the package further comprises some encapsulating material enclosing the first conductive wires and the
5 second conductive wires.